



2023 Society Award Winners

[Congratulations to the IMAPS 2023 Society Award Winners!](#)

IMAPS is proud to recognize its members with a robust awards tradition. IMAPS has many deserving members who have given their time, energy, and expertise to ensure our industry has a robust future. Every year IMAPS members recognize the Society's members who have done such notable work that they deserve the distinction of the Society's awards. Our portfolio of awards publicly acknowledges each honoree's significant impacts on the membership and the microelectronics packaging industry.



**Fellow of the Society
Award**

Tom Terlizzi

Tom Terlizzi is Vice President at GM Systems a Microelectronics Marketing/Sales and Technology consulting firm. For over 40 years, he has designed and developed Power management systems, Single board computers, hybrids, COB modules, Chiplets, MCM's, ICs, RF modules, for military, aerospace, telecom markets at Aeroflex, Norden/UTC, General Instrument. He spearheaded ISO9000 and Military quality certifications including Mil-PRF-38534 at Aeroflex. Tom's activities at ISHM/IMAPS include serving as President and Education chairman for the ISHM/IMAPS Metro Chapter and presenting at the Keystone, Yankee, Metro, New England chapters and presenting PDC courses at IMAPs International symposium and the Metro Chapter to mention a few.

He received a BEE from CCNY and a MSEE from Polytechnic-NYU & has published several articles, papers and presented tutorials at international conferences, edited books on electronic packaging, consulted for the DoD on advanced electronic packaging as well as teaching microelectronics at the US Army Signal School.